

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	R_{thJA}	minimal footprint ¹⁾	-	-	250	K/W
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Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}$, $I_D=-250\text{ }\mu\text{A}$	-20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=-11\text{ }\mu\text{A}$	-1.2	-0.9	-0.6	
Drain-source leakage current	I_{DSS}	$V_{DS}=-20\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$	-	-	-1	μA
		$V_{DS}=-20\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=150\text{ °C}$	-	-	-100	
Gate-source leakage current	I_{GSS}	$V_{GS}=-12\text{ V}$, $V_{DS}=0\text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=2.5\text{ V}$, $I_D=-1.1\text{ A}$	-	166	280	$\text{m}\Omega$
		$V_{GS}=4.5\text{ V}$, $I_D=-1.5\text{ A}$	-	105	150	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}$, $I_D=1.18\text{ A}$	-	4.5	-	S

¹⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide, 70 μm thick and 20mm long; they are present on both sides of the PCB.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V},$ $V_{DS}=-15\text{ V}, f=1\text{ MHz}$	-	260	346	pF
Output capacitance	C_{oss}		-	102	135	
Reverse transfer capacitance	C_{rss}		-	85	128	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=-10\text{ V},$ $V_{GS}=-4.5\text{ V},$ $I_D=-1.5\text{ A}, R_G=6\ \Omega$	-	6.7	-	ns
Rise time	t_r		-	9.7	-	
Turn-off delay time	$t_{d(off)}$		-	14.5	-	
Fall time	t_f		-	14.0	-	

Gate Charge Characteristics

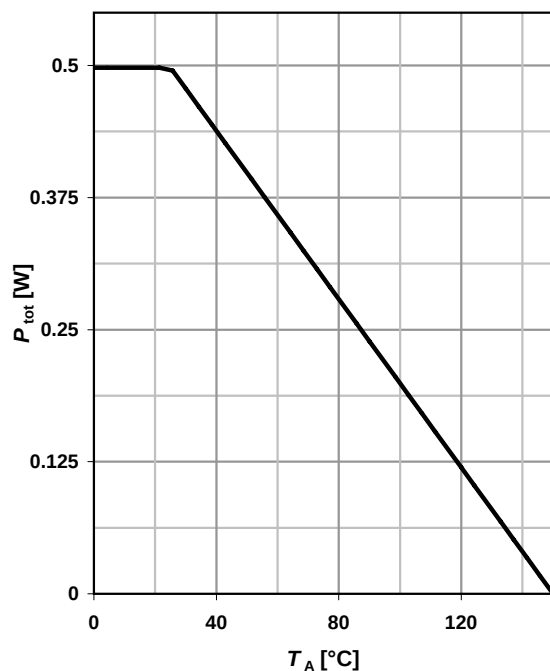
Gate to source charge	Q_{gs}	$V_{DD}=16\text{ V},$ $I_D=-1.5\text{ A},$ $V_{GS}=0\text{ to }-4.5\text{ V}$	-	-0.49	-	nC
Gate to drain charge	Q_{gd}		-	-1.9	-	
Gate charge total	Q_g		-	-3.6	-	
Gate plateau voltage	$V_{plateau}$		-	-1.9	-	V

Reverse Diode

Diode continuous forward current	I_S	$T_A=25\text{ }^\circ\text{C}$	-	-	-0.5	A
Diode pulse current	$I_{S,pulse}$		-	-	-6	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=-1.5\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	-0.8	-1.1	V
Reverse recovery time	t_{rr}	$V_R=10\text{ V}, I_F=-1.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	21.0	-	ns
Reverse recovery charge	Q_{rr}		-	-3.7	-	nC

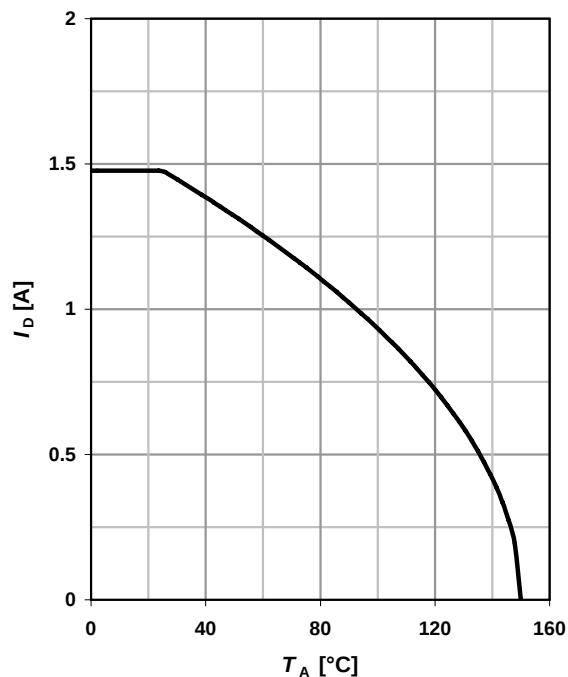
1 Power dissipation

$$P_{\text{tot}} = f(T_A)$$



2 Drain current

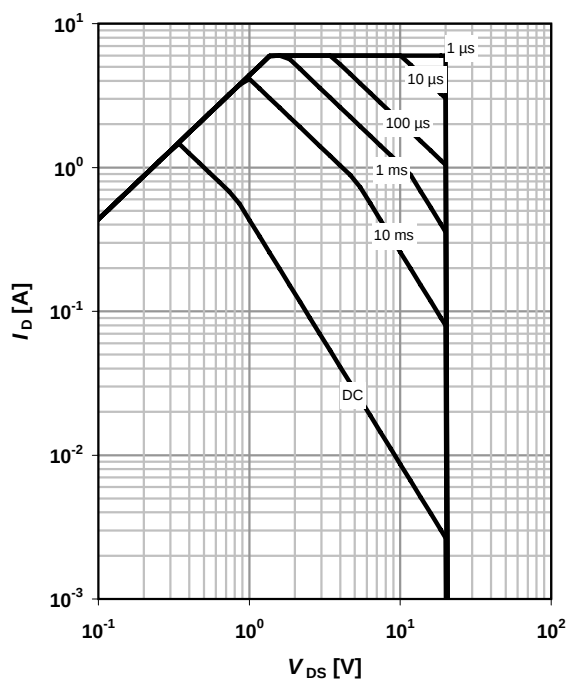
$$I_D = f(T_A); V_{GS} \leq -4.5 \text{ V}$$



3 Safe operating area

$$I_D = f(V_{DS}); T_A = 25^\circ\text{C}; D = 0$$

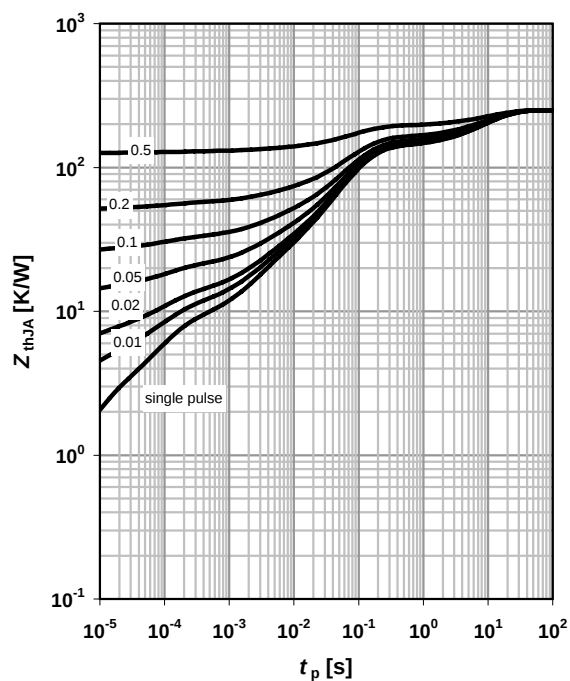
parameter: t_p



4 Max. transient thermal impedance

$$Z_{\text{thJA}} = f(t_p)$$

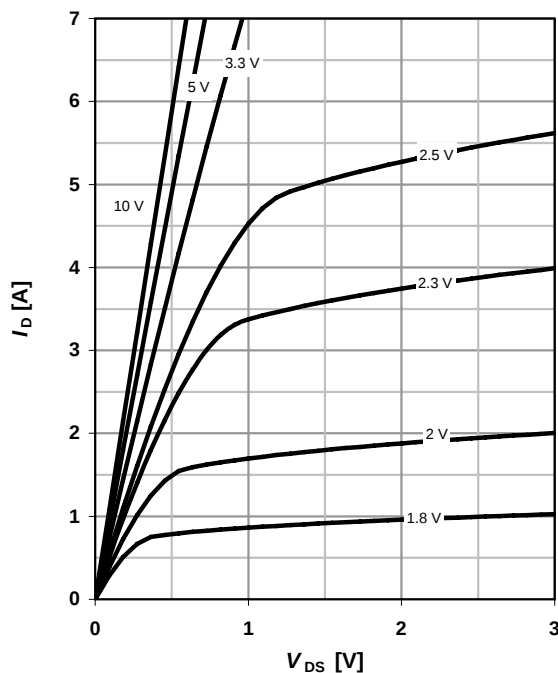
parameter: $D = t_p/T$



5 Typ. output characteristics

$$I_D = f(V_{DS}); T_J = 25^\circ\text{C}$$

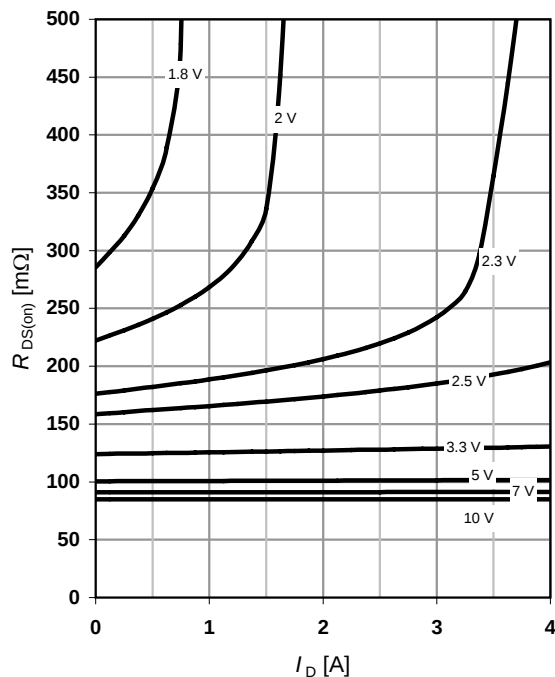
parameter: V_{GS}



6 Typ. drain-source on resistance

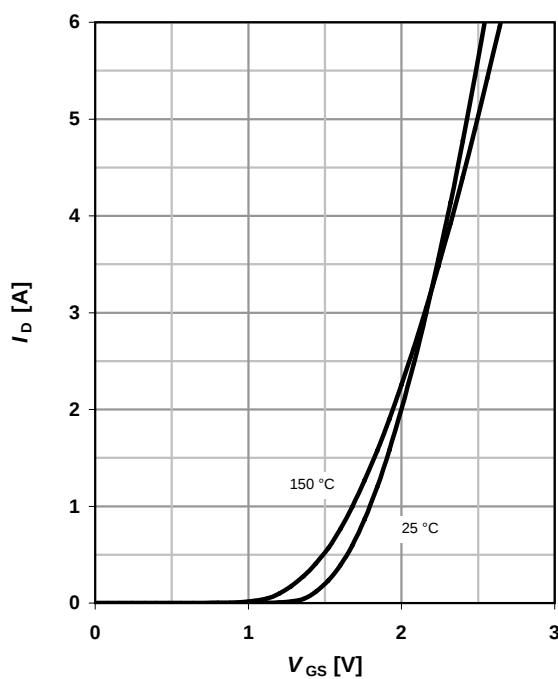
$$R_{DS(on)} = f(I_D); T_J = 25^\circ\text{C}$$

parameter: V_{GS}



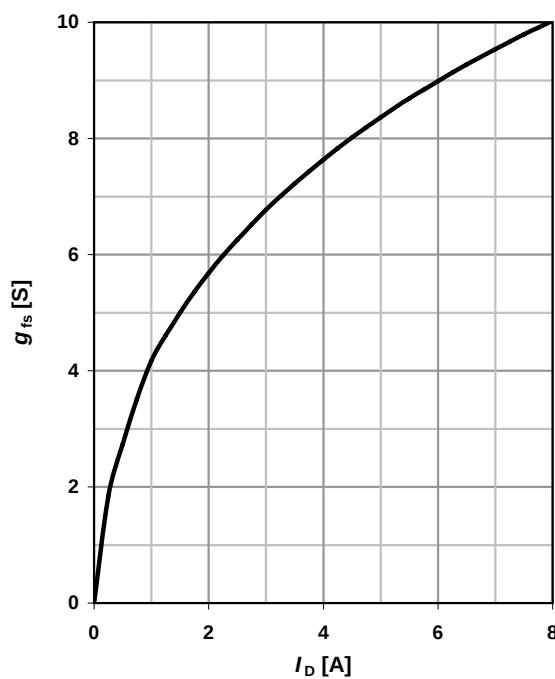
7 Typ. transfer characteristics

$$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$$



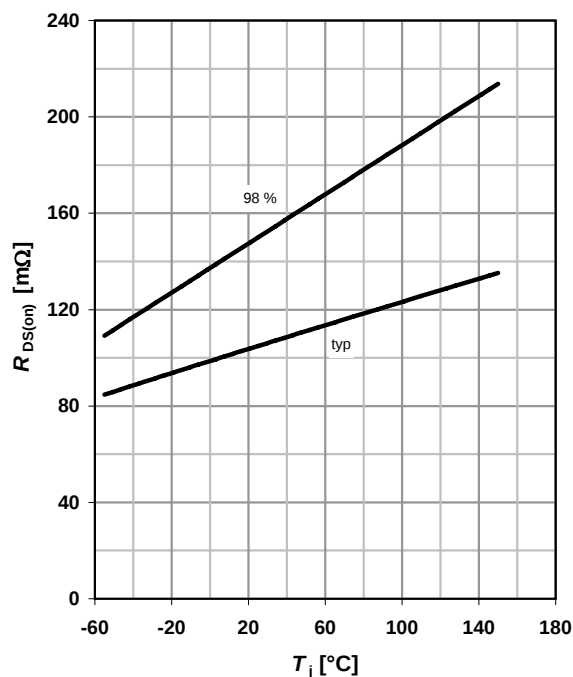
8 Typ. forward transconductance

$$g_{fs} = f(I_D); T_J = 25^\circ\text{C}$$



9 Drain-source on-state resistance

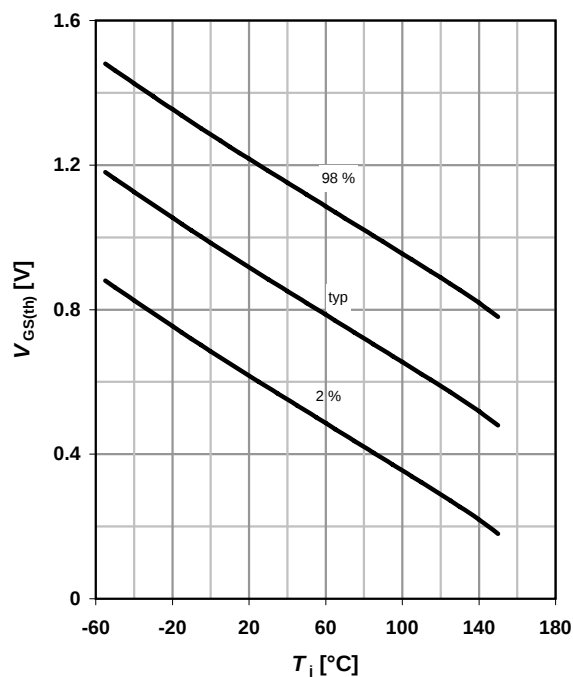
$$R_{DS(on)} = f(T_j); I_D = -1.5 \text{ A}; V_{GS} = -4.5 \text{ V}$$



10 Typ. gate threshold voltage

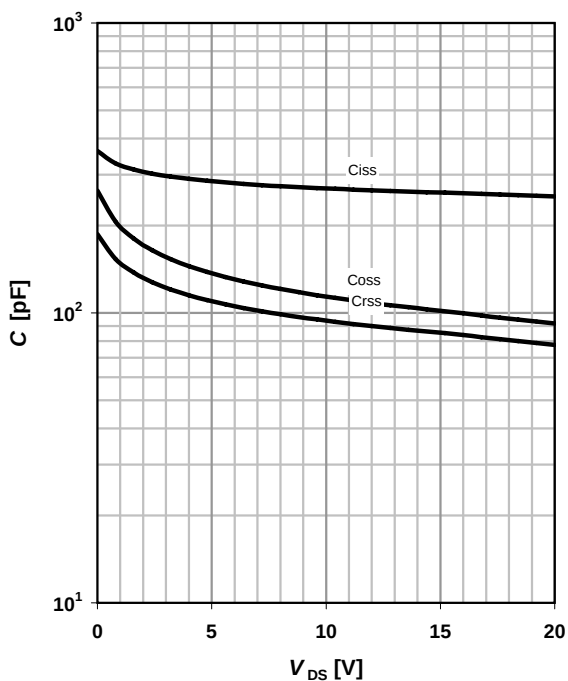
$$V_{GS(th)} = f(T_j); V_{DS} = V_{GS}; I_D = -11 \mu\text{A}$$

parameter: I_D



11 Typ. capacitances

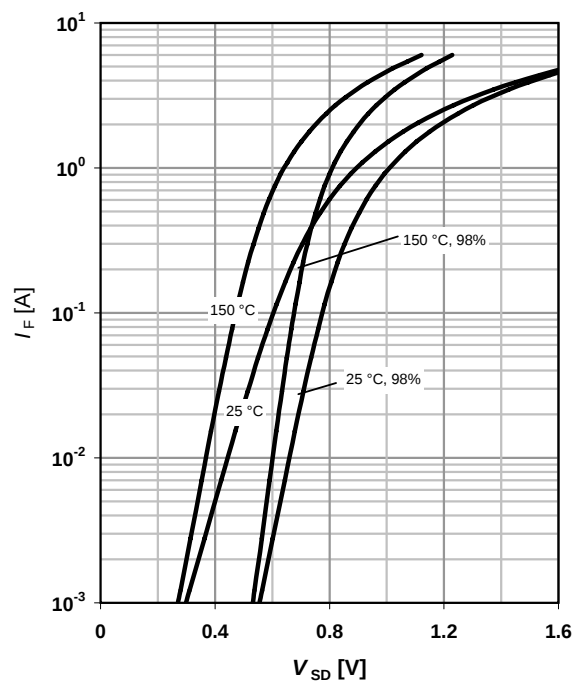
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$$



12 Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

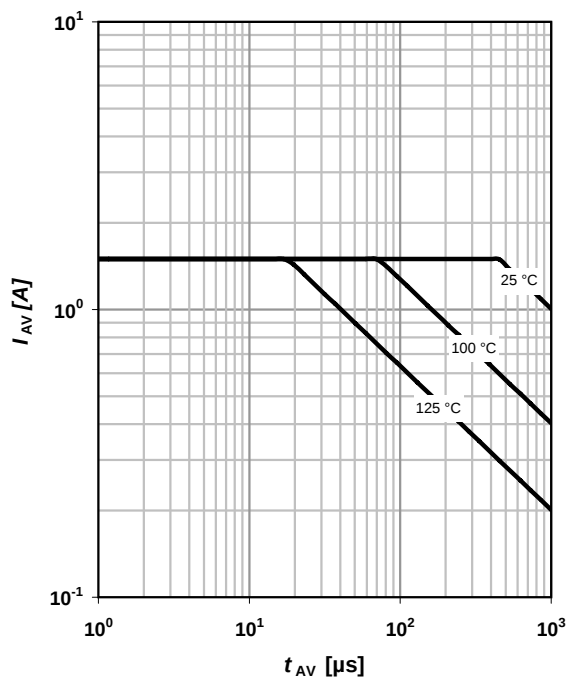
parameter: T_j



13 Avalanche characteristics

$$I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$$

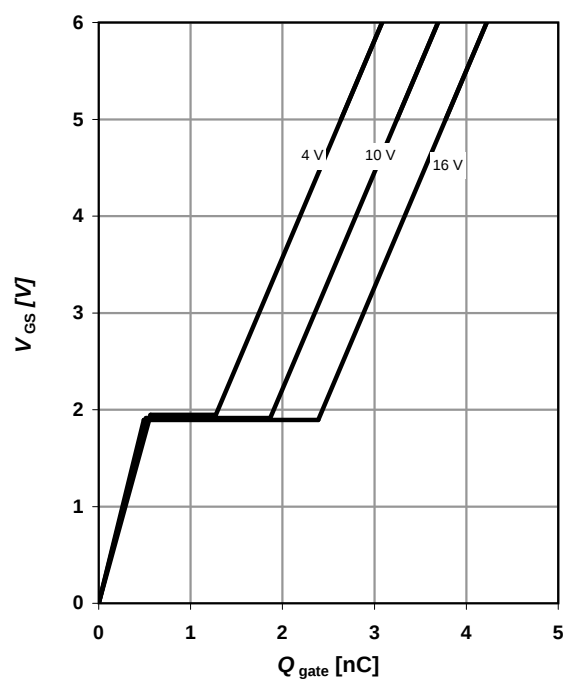
parameter: $T_{j(\text{start})}$



14 Typ. gate charge

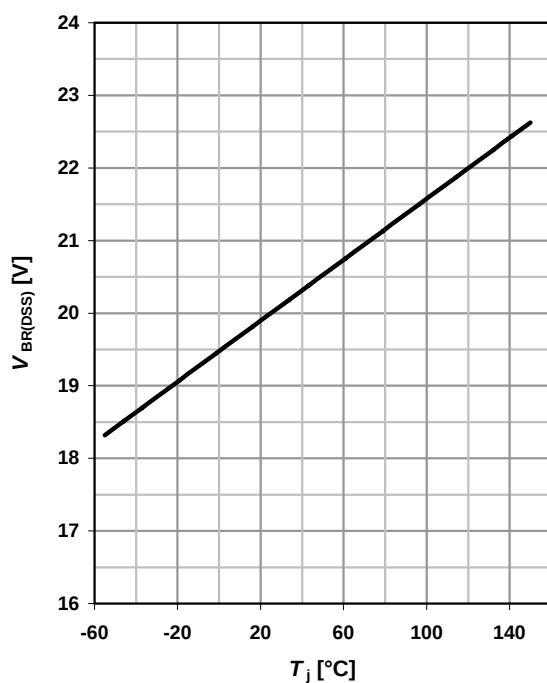
$$V_{GS}=f(Q_{\text{gate}}); I_D=-1.5\ \text{A pulsed}$$

parameter: V_{DD}

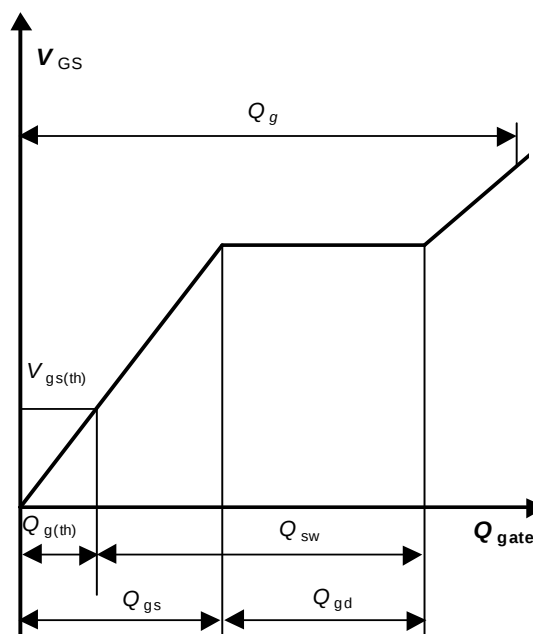


15 Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=250\ \mu\text{A}$$

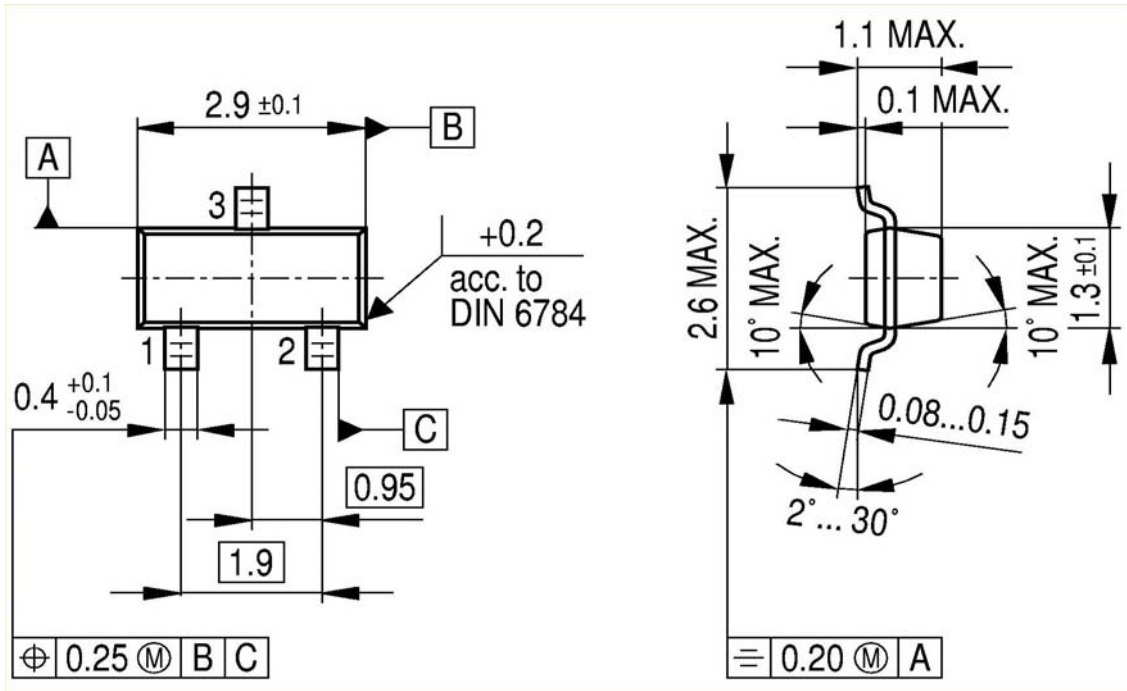


16 Gate charge waveforms

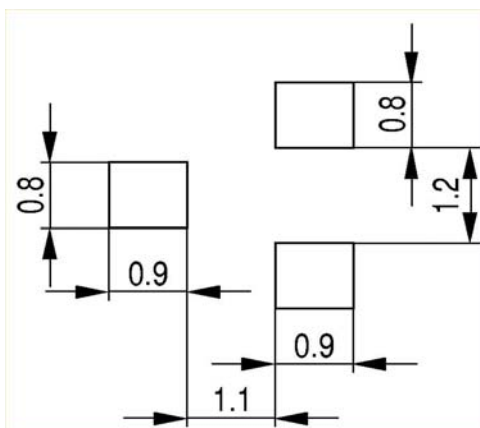


SOT23

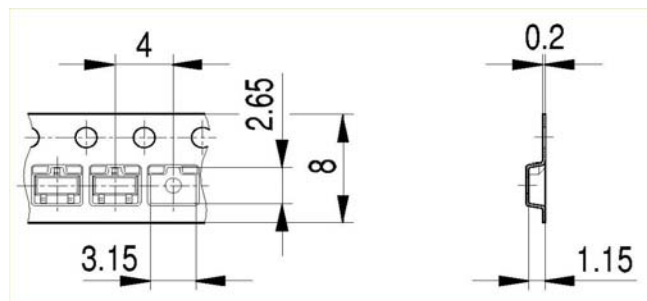
Package Outline:



Footprint:



Packaging:



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